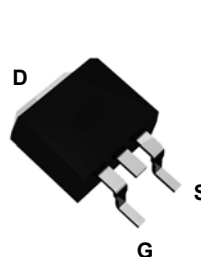
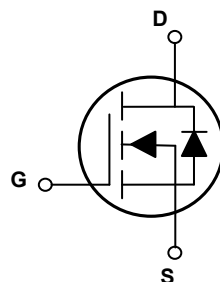


Main Product Characteristics

$V_{(BR)DSS}$	30V
$R_{DS(ON)}$	1.7m Ω (Max.)
I_D	240A



TO-263 (D²PAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFT3002 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-to-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, @ Steady-State ($T_C=25^{\circ}\text{C}$) ¹	I_D	240	A
Continuous Drain Current, @ Steady-State ($T_C= 100^{\circ}\text{C}$) ¹		169	A
Pulsed Drain Current ($T_C=25^{\circ}\text{C}$) ²	I_{DM}	960	A
Power Dissipation ($T_C=25^{\circ}\text{C}$) ³	P_D	297	W
Single Pulse Avalanche Energy	E_{AS}	1156	mJ
Single Pulse Current	I_{AS}	68	A
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.42	$^{\circ}\text{C/W}$
Operating Junction and Storage Temperature Range	T_J / T_{STG}	-55 to +150	$^{\circ}\text{C}$
Soldering Temperature (SMD)	T_{sld}	260	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1.0	μA
		$V_{DS}=30V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	100	
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	1.3	1.7	$m\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	2.1	2.8	
Gate-to-Source Forward Leakage	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	-	2.5	V
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	11153	-	pF
Output Capacitance	C_{oss}		-	1305	-	
Reverse Transfer Capacitance	C_{rss}		-	1105	-	
Total Gate Charge ^{4,5}	Q_g	$I_D=20A, V_{DD}=15V, V_{GS}=10V$	-	204	-	nC
Gate-to-Source Charge ^{4,5}	Q_{gs}		-	31.6	-	
Gate-to-Drain ("Miller") Charge ^{4,5}	Q_{gd}		-	43	-	
Turn-On Delay Time ^{4,5}	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=6\Omega, I_D=20A$	-	20	-	nS
Rise Time ^{4,5}	T_r		-	18	-	
Turn-Off Delay Time ^{4,5}	$T_{d(off)}$		-	43	-	
Fall Time ^{4,5}	T_f		-	15	-	
Gate Resistance	R_g	$f=1\text{MHz}$	-	1.1	-	Ω
Drain-Source Ratings and Characteristics						
Continuous Source Current (Body Diode)	I_S	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	240	A
Diode Pulse Current	$I_{S,pulse}$		-	-	960	A
Diode Forward Voltage	V_{SD}	$I_S=20A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time ⁴	t_{rr}	$I_S=20A, V_{GS}=0V, V_R=20V, di_F/dt=100A/\mu s$	-	43	-	nS
Reverse Recovery Charge ⁴	Q_{rr}		-	39	-	nC

Note:

1. The rated value only refers to the maximum absolute value under the case temperature of 25°C in the manual, if the case temperature is higher than 25°C , the frequency needs to be reduced according to the actual environmental conditions.
2. Pulse time of $5\mu s$, pulse width limited by maximum junction temperature.
3. The dissipated power value will change with the temperature. When it is greater than 25°C , the dissipated power value will decrease by $2.4W/^\circ\text{C}$ for every 1 degree of temperature increase.
4. Pulse test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
5. Basically unaffected by operating temperature.

Typical Electrical and Thermal Characteristic Curves

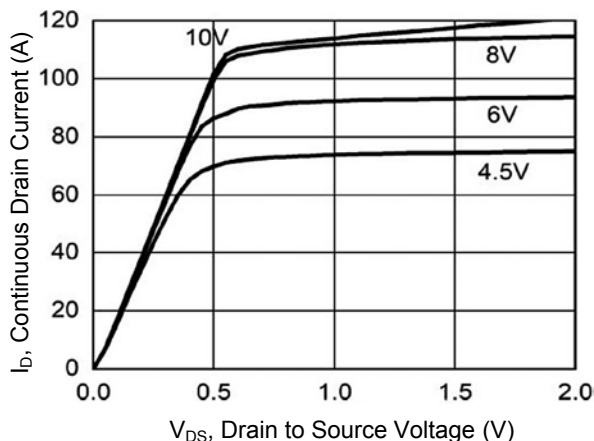


Figure 1. Output Characteristics

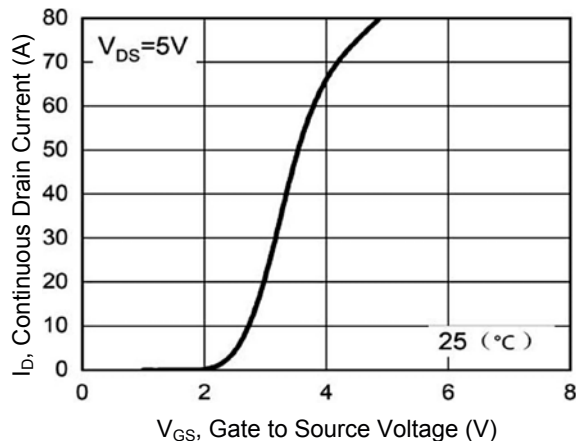


Figure 2. Transfer Characteristics

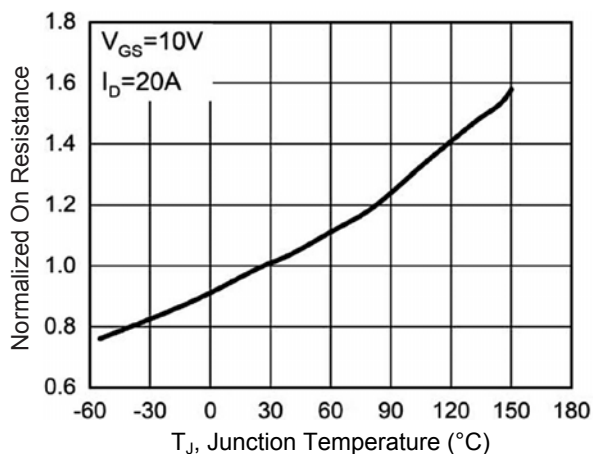


Figure 3. Normalized On-Resistance vs. T_J

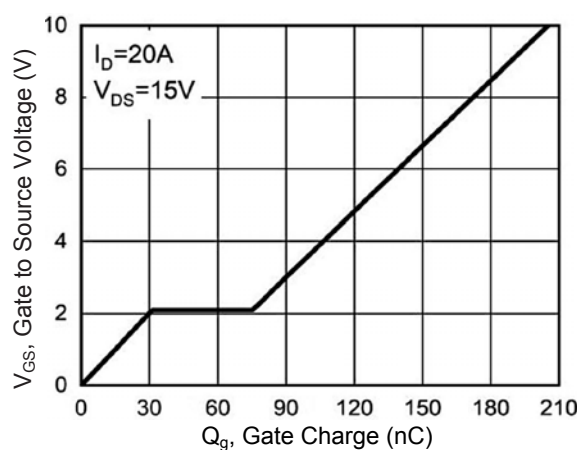


Figure 4. Gate Charge Characteristics

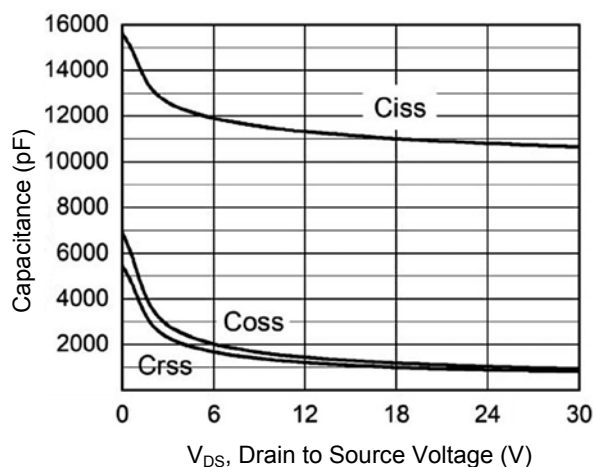


Figure 5. Capacitance Characteristics

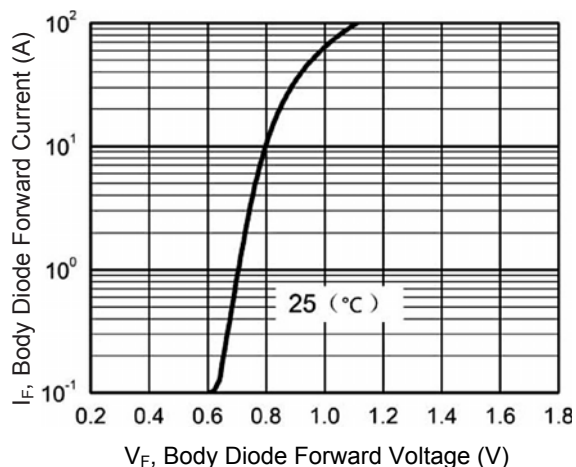
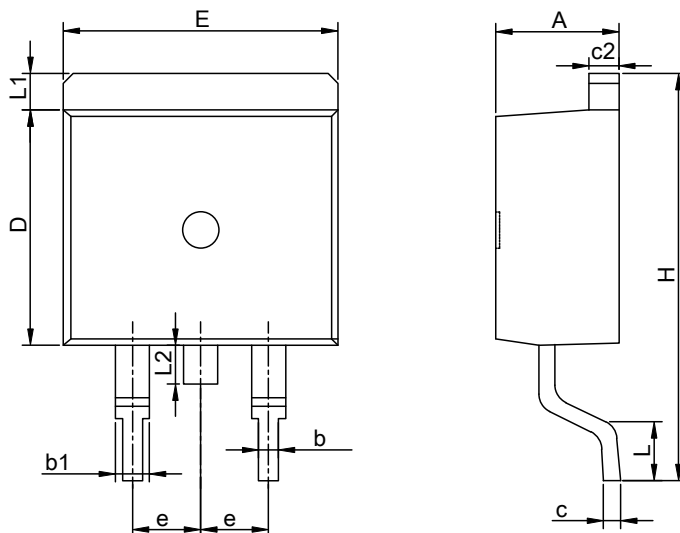


Figure 6. Body Diode Characteristics

Package Outline Dimensions TO-263 (D²PAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.30	4.90	0.169	0.193
b	0.70	0.95	0.028	0.037
b1	1.07	1.50	0.042	0.059
c	0.28	0.60	0.011	0.024
c2	1.17	1.37	0.046	0.054
D	8.40	9.35	0.331	0.368
E	9.80	10.45	0.386	0.411
e	2.54 BSC		0.100 BSC	
H	14.70	16.30	0.579	0.642
L	2.00	3.80	0.079	0.150
L1	0.97	1.42	0.038	0.056
L2	-	1.75	-	0.069

Order Information

Device	Package	Marking	Carrier	Quantity
GSFT3002	TO-263 (D ² PAK)	T3002	Tape & Reel	800 Pcs / Reel